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CST Announces Simplified Workflow for Full 3D Simulation in Cadence SiP Flow

Cadence and CST present webcast demonstrating advances resulting from technical cooperation

May 20th, 2010, Computer Simulation Technology (CST) announces closer cooperation and webcast with Cadence Design Systems, Inc.

To address increasing customer demand for integrated layout and 3D full wave analysis, CST and Cadence are collaborating to provide a best in class solution. A webcast on June 23 will demonstrate the integration.

As multiband devices shrink and frequencies increase, layout of packages, system in packages (SiP) and PCBs is becoming increasingly critical to maintain good signal and power integrity and to meet radiated emission requirements. Rule checkers can help to some extent, but electromagnetic field simulators are required to see the full picture, both in pre layout analysis and post-layout verification. Most layout tools have 2D simulators available that can offer good insights, but for high accuracy and to address layouts with non-planar elements such as wirebonds, a full 3D simulator is mandatory.

CST has offered a plug-in to Cadence tools for some years and more recently a direct import has become available that offers component recognition, layer editing and net and area selection. A major collaborative project now enables Cadence layout engineers to stay within their familiar environment while performing a full wave 3D extraction and EM analysis in the background. Results are back annotated to the Cadence environment. This "EDA centric" viewpoint vastly simplifies the workflow required to achieve design goals.

"Simplifying the workflow for layout design and analysis will bring big benefits to the engineer working to get his designs accepted," stated Martin Timm, Director of Marketing, CST. "Not having to learn a new environment or pass the design on to another department will save time and increase overall throughput significantly."

"With increasing numbers of complex, multi-die packages being designed that run at GHz frequencies, package designers now require 3D full wave extraction of IC package structures," commented Brad Griffin, Product Management Director, SiP and IC Packaging, Cadence Design Systems. "The seamless integration of CST's proven 3D full wave extraction engine with the Cadence SiP Signal and Power Integrity solution, unites two recognized leaders into a simplified IC package design flow."

More information on and webcast registration for "Integrated 3D Full-Wave Analysis of Mixed Signal 3D Packages" can be found here: <http://www.secure-register.net/flyer.php?id=1127>

About CST

CST develops and markets software for the simulation of electromagnetic fields. Its products allow you to characterize, design and optimize electromagnetic devices all before going into the lab or measurement chamber. The extensive range of tools integrated in CST STUDIO SUITE® enables numerous applications to be analyzed without leaving the user-friendly CST design environment and can offer additional security through cross verification. CST's customers operate in industries as diverse as Defense, Telecommunications, Automotive, Electronics, and Medical Equipment.

More information about CST and its products is available at <http://www.cst.com>.

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Graphics

The CST logo can be downloaded from the news section of CST's website at:

<http://www.cst.com/Content/News/Details.aspx?newsId=153>